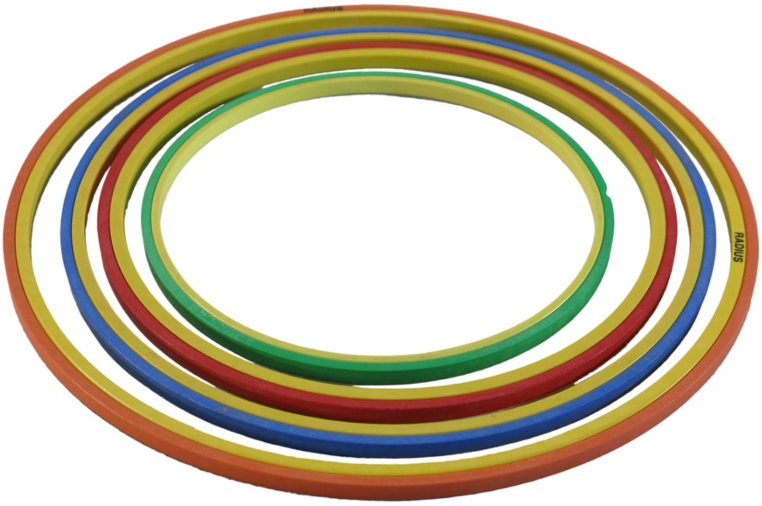
MICROWORLD
Microelectronics Supply Specialist

AP

Grip ring for expansion



Grip ring are used for dicing application, when user needs to make space between dies after dicing.
It will be placed in an expansion machine, and the inner and outer rings will be clamped to keep the tension of the tape. The assembly could be placed in a pick & place machine to remove dies from the tape.

Used for:	Surface finishes:	Options:	When inquiring specify:
• In line wafer handling on expander rings • Wafer back grinding • Wafer mounting • Wafer die sort • Wafer / die pick & place • Wafer / die shipping	• Anodize – non-conductive (colors) • Alodine - conductive (colors) • Decoral - conductive (colors) • Electroless nickel plating - conductive • Hardcoat – non-conductive (colors)	• Custom aluminum and plastic rings upon request • Mark • Die orientation	• Wafer Diameter • Machine Chuck Diameter • Mylar / Film Thickness

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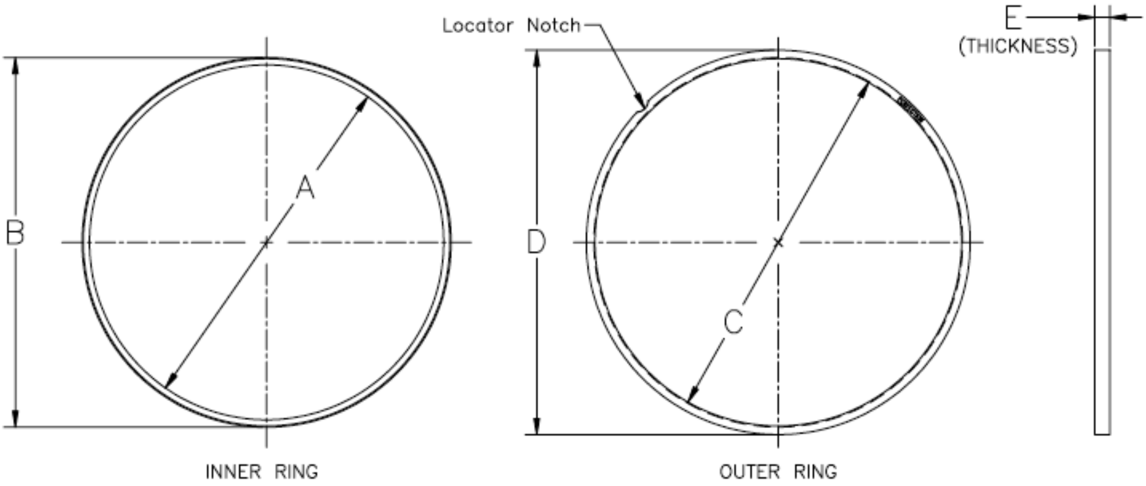
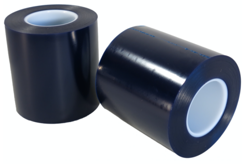
Dimensions

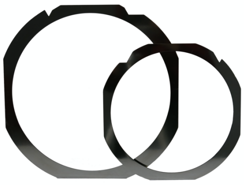


Wafer diameter	Inner ring I.D. / O.D. mm (A / B)	Outer ring I.D. / O.D. mm (C / D)	Ring thickness mm (E)	Locator notch	Ring color OD / ID	Part number
3″ – 75 mm	115.06 / 121.1	120.95 / 126.74	5.99	Yes	Gray / Yellow	AP3
4″ – 100 mm	140.20 / 146.05	145.89 / 151.91	5.99	No	Green / Yellow	AP4
5″ – 125 mm	169.90 / 178.05	177.8 / 185.97	5.99	No	Red / Yellow	AP5
6″ – 150 mm	194.81 / 202.51	202.56 / 210.31	5.99	No	Blue / Yellow	AP6
8″ – 200 mm	224.94 / 233.07	233.12 / 241.25	5.99	No	Orange / Yellow	AP8

Material: Polycarbonate
ESD insulation (measured): < 10^{e}12 Ω



Tapes



Frames

UH130 expander